Very Low Forward Voltage Trench-based Schottky Rectifier

Exceptionally Low $V_F = 0.39$ V at $I_F = 5$ A

Features

- Fine Lithography Trench–based Schottky Technology for Very Low Forward Voltage and Low Leakage
- Fast Switching with Exceptional Temperature Stability
- Low Power Loss and Lower Operating Temperature
- Higher Efficiency for Achieving Regulatory Compliance
- Low Thermal Resistance
- High Surge Capability
- This is a Pb–Free Device

Typical Applications

- Switching Power Supplies including Notebook / Netbook Adapters, ATX and Flat Panel Display
- High Frequency and DC-DC Converters
- Freewheeling and OR-ing diodes
- Reverse Battery Protection
- Instrumentation

Mechanical Characteristics

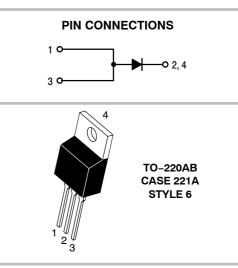
- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94–0 @ 0.125 in
- Weight (Approximately): 1.9 grams
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Maximum for 10 sec



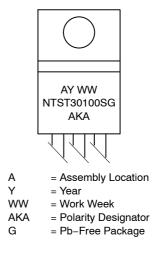
ON Semiconductor®

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VERY LOW FORWARD VOLTAGE, LOW LEAKAGE SCHOTTKY BARRIER RECTIFIERS 30 AMPERES, 100 VOLTS



MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

MAXIMUM RATINGS

Rating		Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	100	V	
Average Rectified Forward Current (Rated V_R , T_C = 105°C)	I _{F(AV)}	30	A	
Peak Repetitive Forward Current (Rated V_R , Square Wave, 20 kHz, T_C = 95°C)	I _{FRM}	60	A	
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	250	A	
Operating Junction Temperature	TJ	-40 to +150	°C	
Storage Temperature	T _{stg}	-65 to +175	°C	
Voltage Rate of Change (Rated V _R)	dv/dt	10,000	V/µs	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Maximum Thermal Resistance Junction-to-Case Junction-to-Ambient	R _{θJC}	2.0	°C/W
	R _{θJA}	70	°C/W

ELECTRICAL CHARACTERISTICS

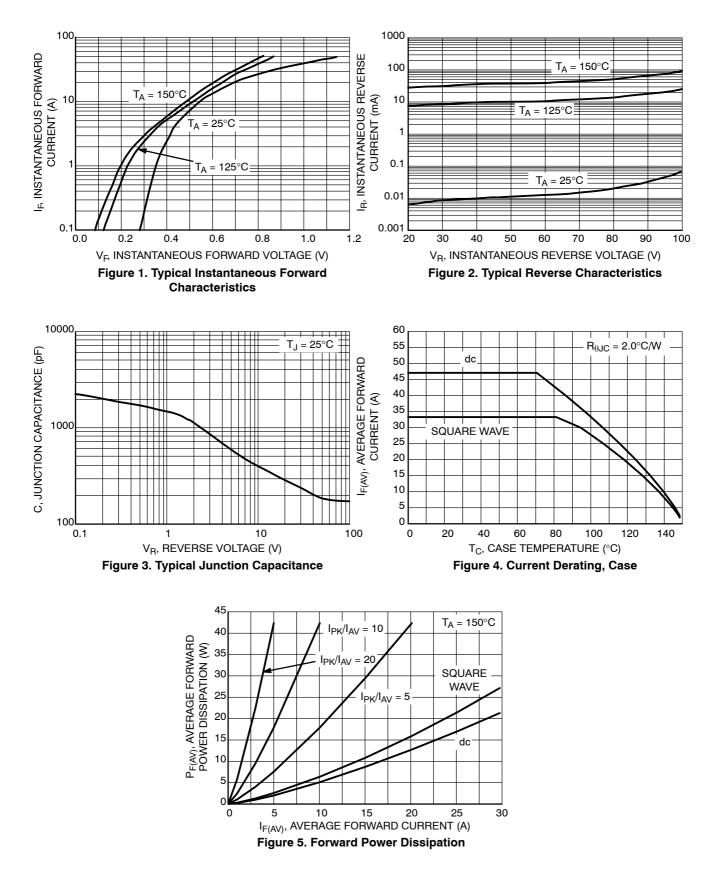
Rating	Symbol	Тур	Max	Unit
Maximum Instantaneous Forward Voltage (Note 1) $(I_F = 5 A, T_J = 25^{\circ}C)$ $(I_F = 10 A, T_J = 25^{\circ}C)$ $(I_F = 30 A, T_J = 25^{\circ}C)$ $(I_F = 5 A, T_J = 125^{\circ}C)$	v _F	0.47 0.55 0.84 0.39	_ _ 0.95 _	V
$(I_F = 10 \text{ A}, T_J = 125^{\circ}\text{C})$ $(I_F = 30 \text{ A}, T_J = 125^{\circ}\text{C})$		0.51 0.7	_ 0.78	
Maximum Instantaneous Reverse Current (Note 1) $(V_R = 70 \text{ V}, T_J = 25^{\circ}\text{C})$ $(V_R = 70 \text{ V}, T_J = 125^{\circ}\text{C})$	I _R	27 11		μA mA
(Rated dc Voltage, $T_J = 25^{\circ}C$) (Rated dc Voltage, $T_J = 125^{\circ}C$)		70 23	1000 45	μA mA

1. Pulse Test: Pulse Width = 300 $\mu s,$ Duty Cycle \leq 2.0%

ORDERING INFORMATION

Device	Package	Shipping
NTST30100SG	TO-220AB (Pb-Free)	50 Units / Rail

TYPICAL CHARACTERISTICS



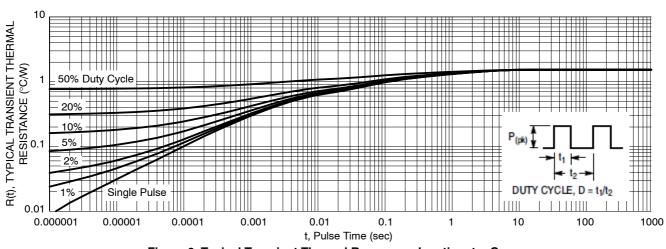
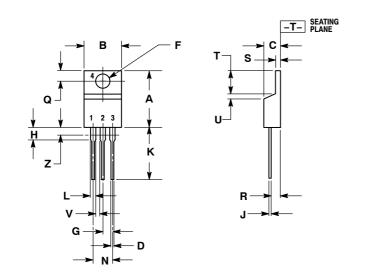


Figure 6. Typical Transient Thermal Response, Junction-to-Case

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 ISSUE AF



NOTES:

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 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: INCH.

CONTROLLING DIMENSION: INCH. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.014	0.025	0.36	0.64
Κ	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
Ν	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
۷	0.045		1.15	
Ζ		0.080		2.04

STYLE 6: PIN 1. ANODE

2. CATHODE 3. ANODE

4. CATHODE

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